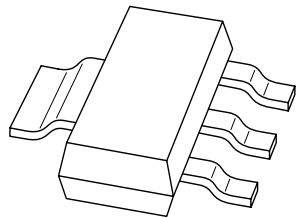


# DATA SHEET



## **PZT4401** NPN switching transistor

Product data sheet

1999 May 10

# NPN switching transistor

# PZT4401

### FEATURES

- High current (max. 600 mA)
- Low voltage.

### APPLICATIONS

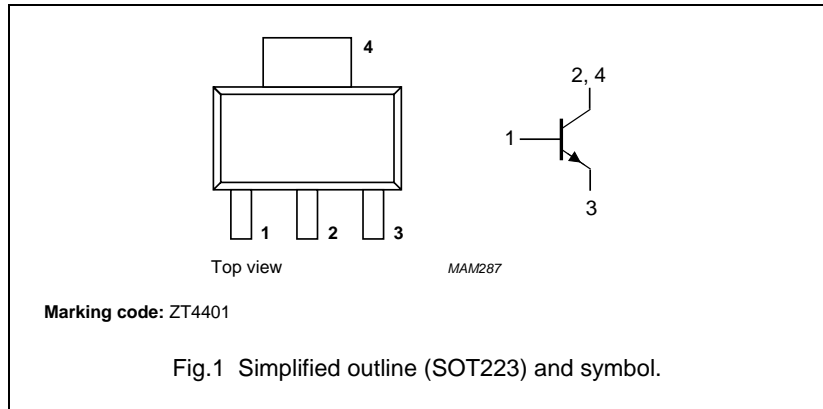
- Switching and linear amplification in industrial and consumer applications.

### DESCRIPTION

NPN switching transistor in a SOT223 plastic package. PNP complement: PZT4403.

### PINNING

PIN	DESCRIPTION
1	base
2, 4	collector
3	emitter



### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	–	60	V
$V_{CEO}$	collector-emitter voltage	open base	–	40	V
$V_{EBO}$	emitter-base voltage	open collector	–	6	V
$I_C$	collector current (DC)		–	600	mA
$I_{CM}$	peak collector current		–	800	mA
$I_{BM}$	peak base current		–	200	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ }^\circ\text{C}$ ; note 1	–	1150	mW
$T_{stg}$	storage temperature		–65	+150	$^\circ\text{C}$
$T_j$	junction temperature		–	150	$^\circ\text{C}$
$T_{amb}$	operating ambient temperature		–65	+150	$^\circ\text{C}$

### Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm<sup>2</sup>. For other mounting conditions, see “Thermal considerations for SOT223 in the General Part of associated Handbook”.

## NPN switching transistor

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## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	109	K/W
$R_{th\ j-s}$	thermal resistance from junction to soldering point		28	K/W

## Note

- Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm<sup>2</sup>. For other mounting conditions, see "Thermal considerations for SOT223 in the General Part of associated Handbook".

## CHARACTERISTICS

$T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified.

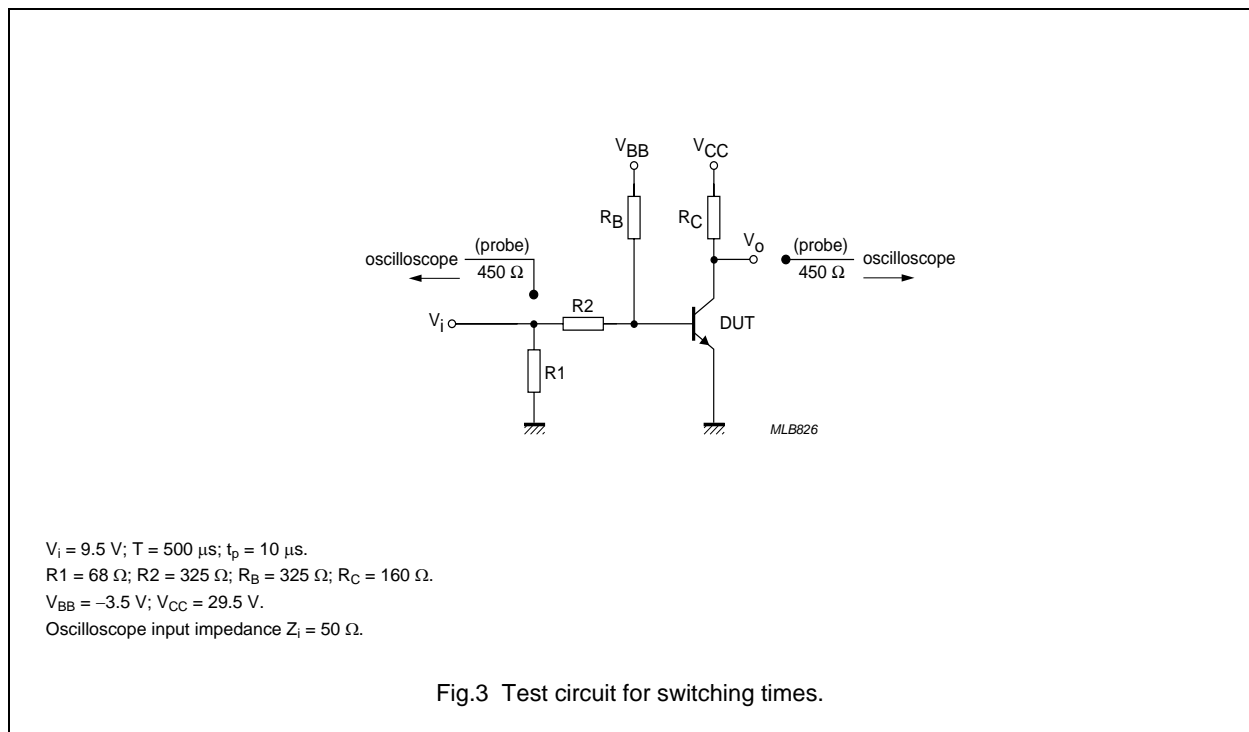
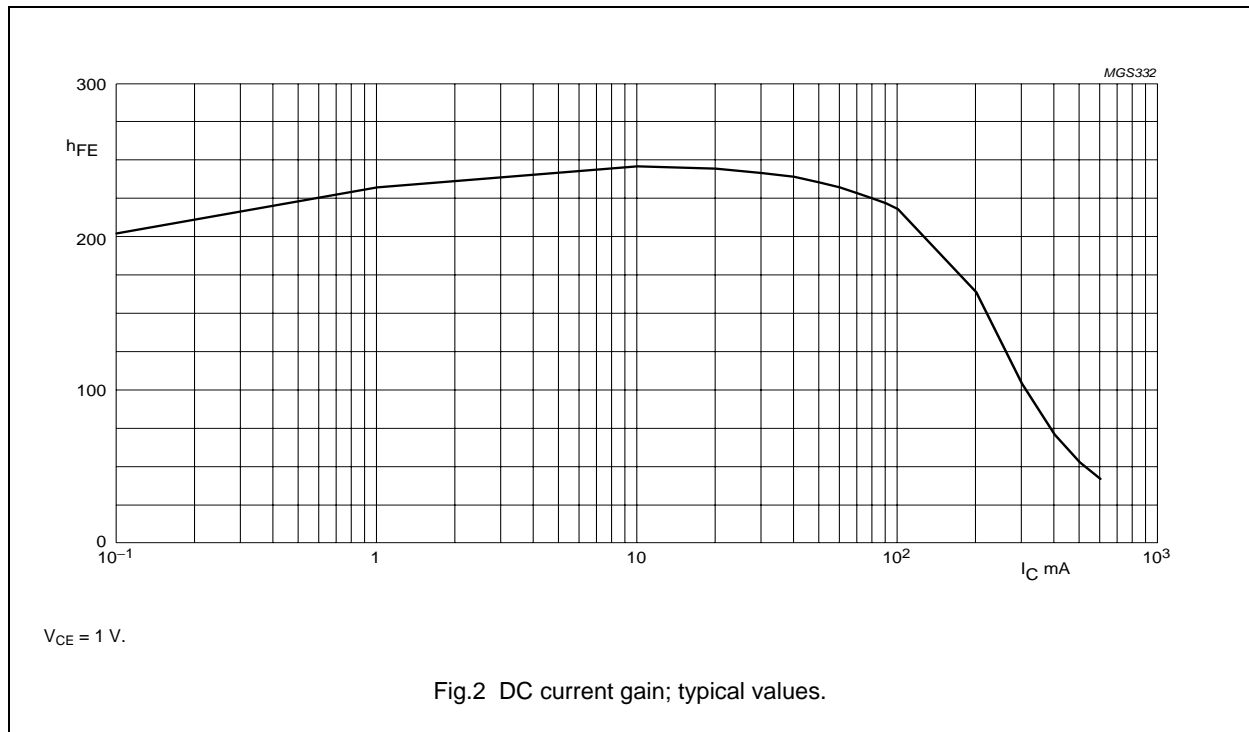
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$I_{CBO}$	collector cut-off current	$I_E = 0$ ; $V_{CB} = 60\text{ V}$	–	50	nA
$I_{EBO}$	emitter cut-off current	$I_C = 0$ ; $V_{EB} = 6\text{ V}$	–	50	nA
$h_{FE}$	DC current gain	$V_{CE} = 1\text{ V}$ ; see Fig.2			
		$I_C = 0.1\text{ mA}$	20	–	
		$I_C = 1\text{ mA}$	40	–	
		$I_C = 10\text{ mA}$	80	–	
		$I_C = 150\text{ mA}$ ; note 1	100	300	
		$V_{CE} = 2\text{ V}$ ; $I_C = 500\text{ mA}$ ; note 1	40	–	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 150\text{ mA}$ ; $I_B = 15\text{ mA}$ ; note 1	–	400	mV
		$I_C = 500\text{ mA}$ ; $I_B = 50\text{ mA}$ ; note 1	–	750	mV
$V_{BEsat}$	base-emitter saturation voltage	$I_C = 150\text{ mA}$ ; $I_B = 15\text{ mA}$ ; note 1	–	950	mV
		$I_C = 500\text{ mA}$ ; $I_B = 50\text{ mA}$ ; note 1	–	1200	mV
$C_c$	collector capacitance	$I_E = i_e = 0$ ; $V_{CB} = 5\text{ V}$ ; $f = 1\text{ MHz}$	–	8	pF
$C_e$	emitter capacitance	$I_C = i_c = 0$ ; $V_{EB} = 500\text{ mV}$ ; $f = 1\text{ MHz}$	–	30	pF
$f_T$	transition frequency	$I_C = 20\text{ mA}$ ; $V_{CE} = 10\text{ V}$ ; $f = 100\text{ MHz}$	250	–	MHz
<b>Switching times (between 10% and 90% levels); see Fig.3</b>					
$t_{on}$	turn-on time	$I_{Con} = 150\text{ mA}$ ; $I_{Bon} = 15\text{ mA}$ ; $I_{Boff} = -15\text{ mA}$ ; $V_{BB} = -3.5\text{ V}$ ; $V_{CC} = 29.5\text{ V}$	–	35	ns
$t_d$	delay time		–	15	ns
$t_r$	rise time		–	20	ns
$t_{off}$	turn-off time		–	250	ns
$t_s$	storage time		–	200	ns
$t_f$	fall time		–	60	ns

## Note

- Pulse test:  $t_p \leq 300\text{ }\mu\text{s}$ ;  $\delta \leq 0.02$ .

NPN switching transistor

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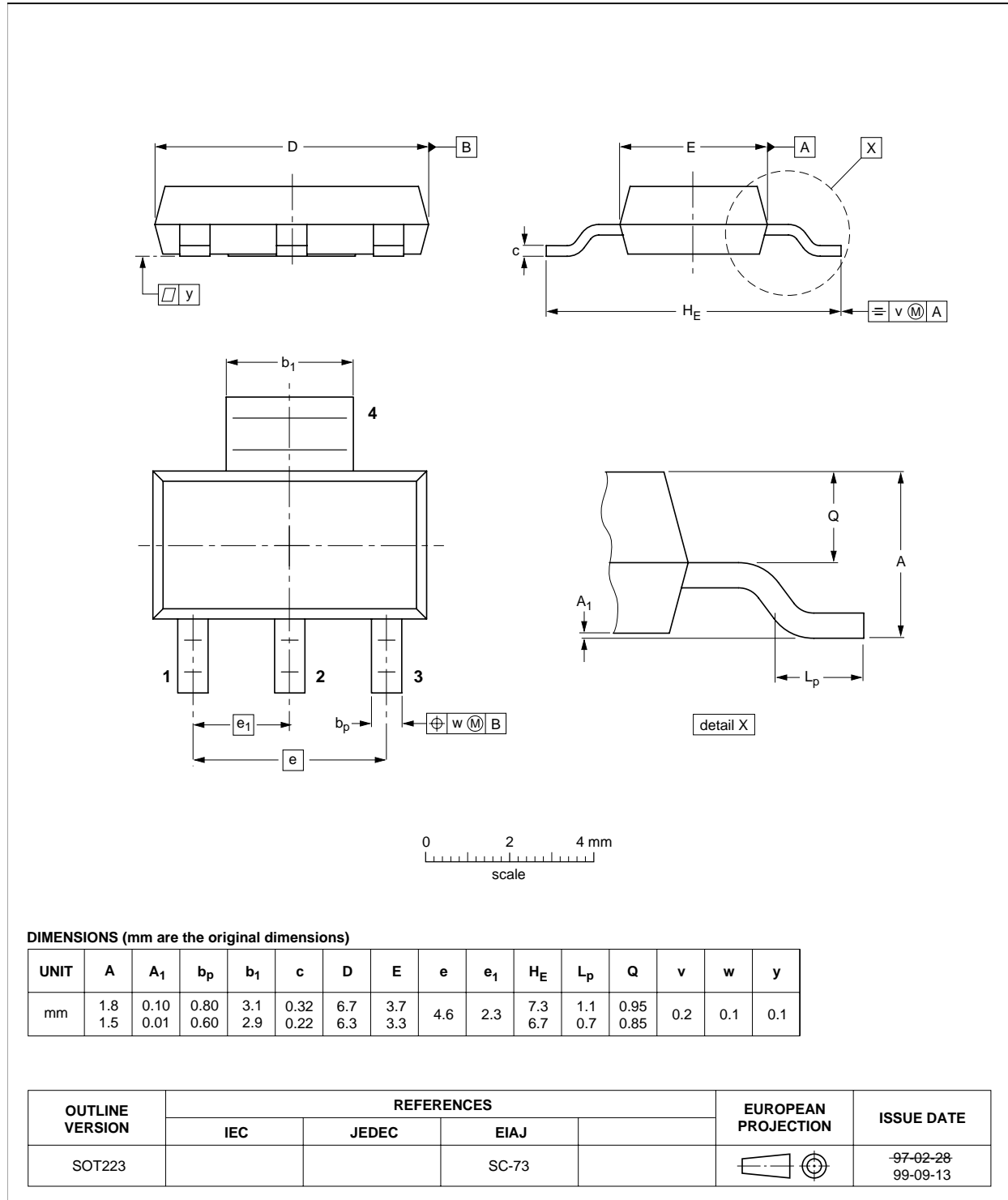
NPN switching transistor

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PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



## NPN switching transistor

PZT4401

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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## **Customer notification**

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## **Contact information**

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